


Date: 4/17/2021

Material Number: EFR32BG12P433F1024IM68-C

Pkg Config.: PK1495

Detailed Device Composition 									
No.	Homogeneous Material	Material Weight (mg)	Material Content	CAS Number	Material Weight (%)	Material Weight (mg)	ppm of Material	Wt % of Total Unit	ppm of Total Unit
1	Bond Wire	0.56	Copper	7440-50-8	96.000	0.535	960000	0.3410	3410
			Gold	7440-57-5	1.000	0.006	10000	0.0036	36
			Palladium	7440-05-3	3.000	0.017	30000	0.0107	107
2	Mold Compound	74.23	Carbon Black	1333-86-4	0.300	0.223	3000	0.1420	1420
			Epoxy Resin A	Proprietary	3.000	2.227	30000	1.4203	14203
			Epoxy Resin B	126-80-7	3.000	2.227	30000	1.4203	14203
			Metal Hydroxide	Proprietary	1.500	1.113	15000	0.7101	7101
			Phenol Resin (Proprietary)	Proprietary	5.000	3.712	50000	2.3672	23672
			Silica	7631-86-9	87.200	64.729	872000	41.2833	412833
3	Plating - External	4.50	Tin	7440-31-5	100.000	4.501	1000000	2.8707	28707
4	Die Attach Epoxy	2.12	Acrylates	Proprietary	4.000	0.085	40000	0.0542	542
			Acrylic Resin	Proprietary	9.000	0.191	90000	0.1220	1220
			Additive	Proprietary	1.500	0.032	15000	0.0203	203
			Butadiene Copolymer	Proprietary	1.000	0.021	10000	0.0136	136
			Epoxy Resin (Proprietary)	Proprietary	2.000	0.042	20000	0.0271	271
			Peroxide	Proprietary	0.500	0.011	5000	0.0068	68
			Polybutadiene Derivative	Proprietary	5.000	0.106	50000	0.0678	678
			Silver	7440-22-4	77.000	1.636	770000	1.0436	10436
5	Leadframe	69.74	Copper	7440-50-8	91.323	63.688	913230	40.6195	406195
			Iron	7439-89-6	2.186	1.524	21860	0.9723	9723
			Lead	7439-92-1	0.005	0.003	50	0.0022	22
			Phosphorous	7723-14-0	0.073	0.051	730	0.0325	325
			Silver	7440-22-4	6.300	4.394	63000	2.8022	28022
			Zinc	7440-66-6	0.113	0.079	1130	0.0503	503
6	Die	5.64	Silicon	7440-21-3	99.800	5.628	998000	3.5893	35893
			Silicon Dioxide	60676-86-0	0.200	0.011	2000	0.0072	72
	Total Unit Weight =	156.79				156.79		100.0000	1000000